

PCB

IMS ALLUMINIUM, COPPER AND NEW MATERIALS

FOR ALL THOSE APPLICATIONS THAT REQUIRE
AN ELEVATED HEAT DISSIPATION

Materials used

CEM3 High Thermal 1 W/m²°k

IMS materials

Substrate: aluminium, copper

Dielectric: ceramic, filled

Copper: 35, 70, 105 µm

Aluminum/dielectric flexible materials,
with ductile copper

Treatments

Drilling: CNC-Punching, Punching

Solder resist: UV-Photografic (with anti
yellowing pigmentations)

Silk-screen

Thickness of base copper:

18-35-70-105 µm

Thickness of base laminate:

From 0,3 - 1,0 - 1,5 - 2,0 - 3 mm

Mechanical finishes:

Milling, Scoring+Jump, Punching, Flaring

Surfaces finishes

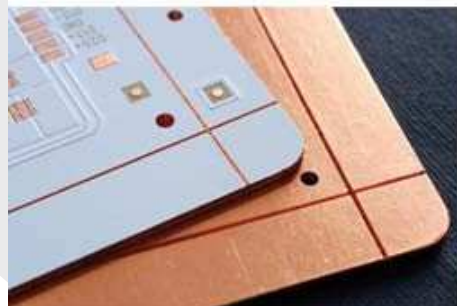
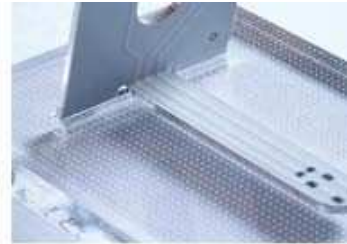
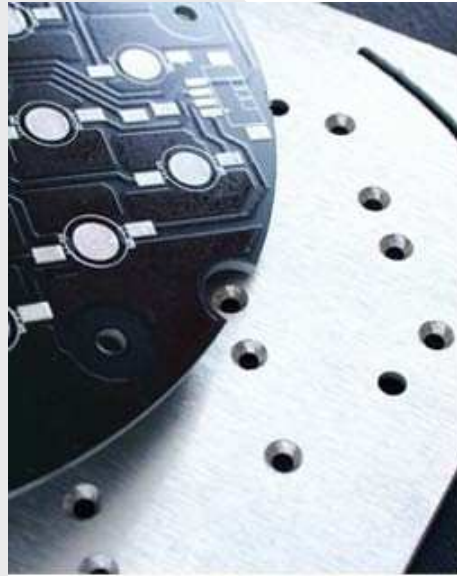
Hal Lead Free, OSP, Immersion SILVER

Electrical test

Low and High voltage, AOI

Approval

UL FILE :e173328



SITEL

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